

DATA SHEET

74F804, 74F1804 Hex 2-input NAND drivers

Product specification

1990 Sep 14

IC15 Data Handbook

Hex 2-input NAND drivers

74F804/1804

FEATURES

- High capacitive drive capability
- Choice of configuration
Corner V_{CC} and GND – 74F804
Center V_{CC} and GND – 74F1804
- Typical propagation delay of 2.5ns

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F804	2.5ns	9mA
74F1804	2.5ns	9mA

INPUT AND OUTPUT
LOADING AND FAN OUT TABLE

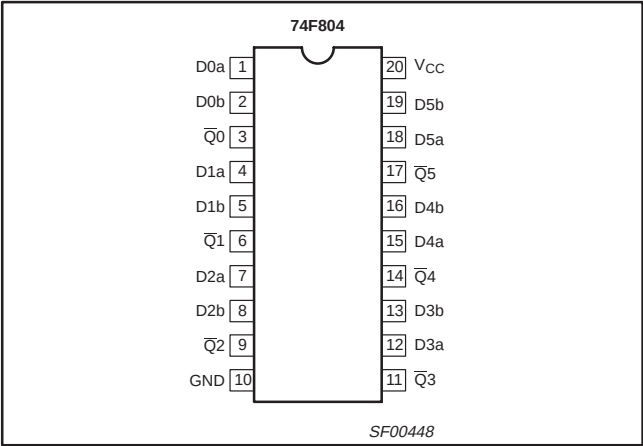
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna – Dnb	Data inputs	1.0/0.033	20µA/20µA
$\overline{Q}0 – \overline{Q}5$	Data outputs	2400/80	48mA/48mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the high state and 0.6mA in the low state.

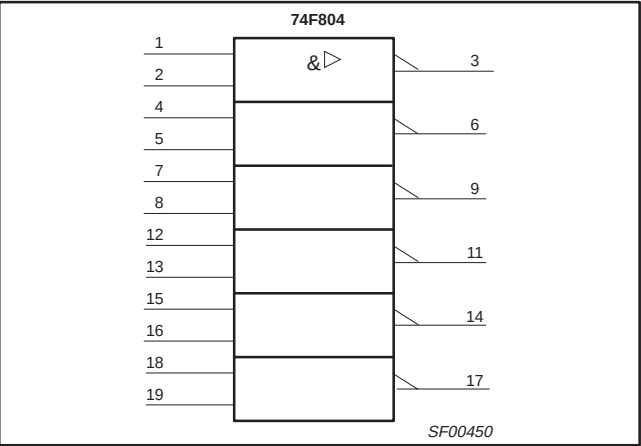
ORDERING INFORMATION

DESCRIPTION	ORDER CODE	PKG DWG #
	COMMERCIAL RANGE V _{CC} = 5V ±10%, T _{amb} = 0°C to +70°C	
20–pin plastic DIP	N74F804N, N74F1804N	SOT146-1
20–pin plastic SOL	N74F804D, N74F1804D	SOT163-1

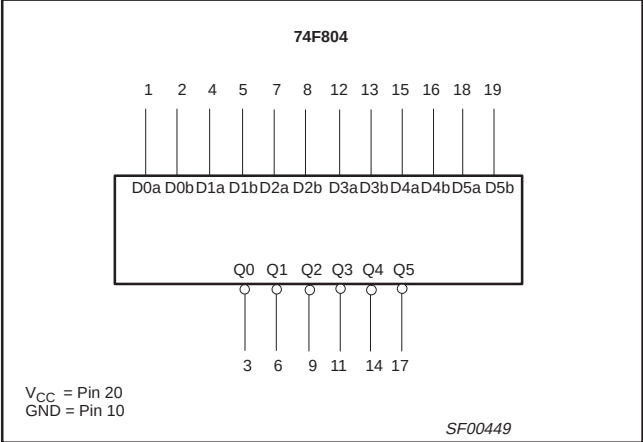
PIN CONFIGURATION



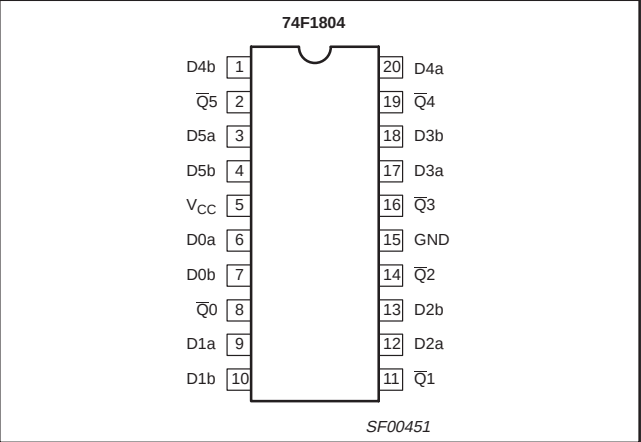
IEC/IEEE SYMBOL



LOGIC SYMBOL



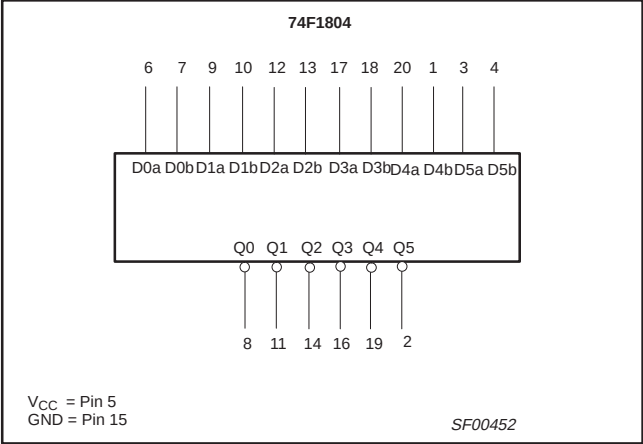
PIN CONFIGURATION



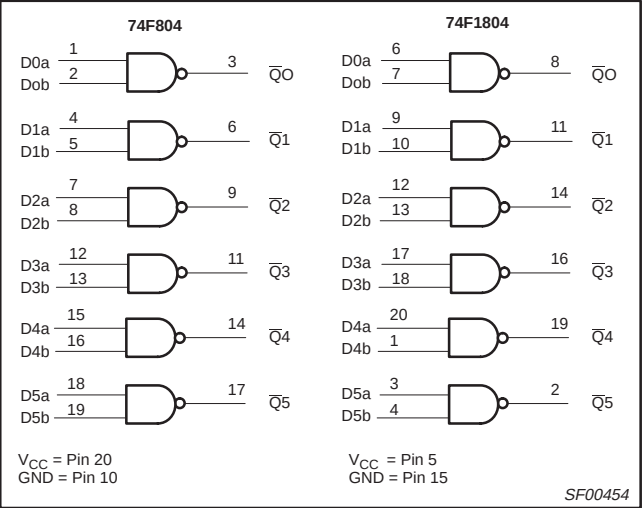
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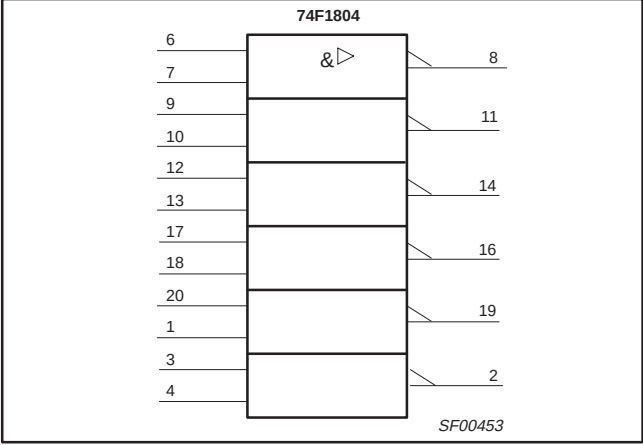
LOGIC SYMBOL



LOGIC DIAGRAM



IEC/IEEE SYMBOL



FUNCTION TABLE

INPUTS		OUTPUT
Da	Db	$\bar{Q}$
H	H	L
L	X	H
X	L	H

NOTES:
H = High voltage level
L = Low voltage level
X = Don't care

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limit set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V _{CC}	Supply voltage	−0.5 to +7.0	V
V _{IN}	Input voltage	−0.5 to +7.0	V
I _{IN}	Input current	−30 to +5	mA
V _{OUT}	Voltage applied to output in high output state	−0.5 to V _{CC}	V
I _{OUT}	Current applied to output in low output state	96	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C
T _{stg}	Storage temperature range	−65 to +150	°C

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RECOMMENDED OPERATING CONDITIONS

SYMBOL UNIT	PARAMETER	LIMITS			$T_A = -40$ to $+85^\circ\text{C}$
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			-18	mA
I_{OH}	High-level output current			-48	mA
I_{OL}	Low-level output current			48	mA
T_{amb}	Operating free air temperature range	0		+70	$^\circ\text{C}$

DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS ¹		LIMITS			UNIT
				MIN	TYP ²	MAX	
V_{OH}	High-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}$	$\pm 10\%V_{CC}$	2.0			V
		$V_{IH} = \text{MIN}, I_{OH} = \text{MAX}$	$\pm 5\%V_{CC}$	2.0			V
V_{OL}	Low-level output voltage	$V_{CC} = \text{MIN}, V_{IL} = \text{MAX}$	$\pm 10\%V_{CC}$		0.38	0.55	V
		$V_{IH} = \text{MIN}, I_{OL} = \text{MAX}$	$\pm 5\%V_{CC}$		0.38	0.55	V
V_{IK}	Input clamp voltage	$V_{CC} = \text{MIN}, I_I = I_{IK}$			-0.73	-1.2	V
I_I	Input current at maximum input voltage	$V_{CC} = \text{MAX}, V_I = 7.0\text{V}$				100	μA
I_{IH}	High-level input current	$V_{CC} = \text{MAX}, V_I = 2.7\text{V}$				20	μA
I_{IL}	Low-level input current	$V_{CC} = \text{MAX}, V_I = 0.5\text{V}$				-20	μA
I_O	Output current ³	$V_{CC} = \text{MAX}$		-60		-160	mA
I_{CC}	Supply current (total)	$I_{CCH} \quad V_{CC} = \text{MAX}$	$V_{IN} = \text{GND}$		2.0	3.0	mA
		$I_{CCL} \quad V_{CC} = \text{MAX}$	$V_{IN} = 4.5\text{V}$		15	20	mA

NOTES:

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at $V_{CC} = 5\text{V}$, $T_{amb} = 25^\circ\text{C}$.
- The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS						UNIT
			T _{amb} = +25°C V _{CC} = +5.0V C _L = 50pF, R _L = 500Ω			T _{amb} = 0°C to +70°C V _{CC} = +5.0V ± 10% C _L = 50pF, R _L = 500Ω			
			MIN	TYP	MAX	MIN	MAX		
t _{PLH} t _{PHL}	Propagation delay D _{na} , D _{nb} to Q _n	Waveform 1	1.0 1.0	2.0 3.0	4.0 4.5	1.0 1.0	4.0 5.0	ns	
t _{sk(n)}	Output skew ^{1,2}	Waveform 2			1.5		1.5	ns	

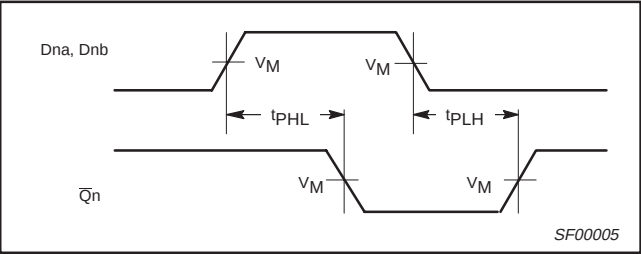
NOTES:

- $[t_{PN} \text{ actual} - t_{PM} \text{ actual}]$ for any output compared to any other output where N and M are either LH or HL.
- Skew times are valid only under same test conditions (temperature, V_{CC} , loading, etc.,).

Hex 2-input NAND drivers

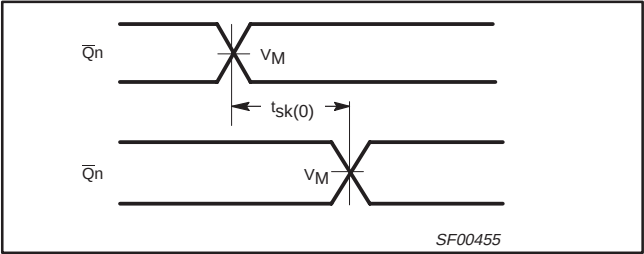
74F804/1804

AC WAVEFORMS



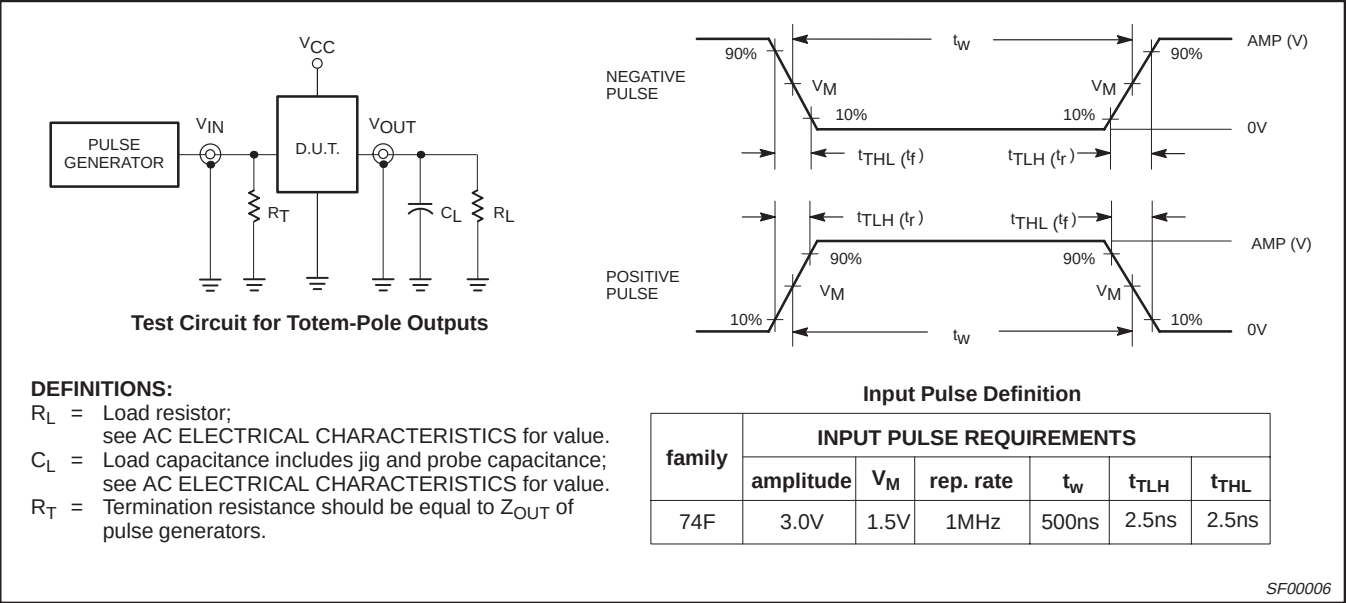
Waveform 1. Propagation delay for inverting outputs

NOTE: For all waveforms, $V_M = 1.5V$.



Waveform 2. Output skew

TEST CIRCUIT AND WAVEFORMS



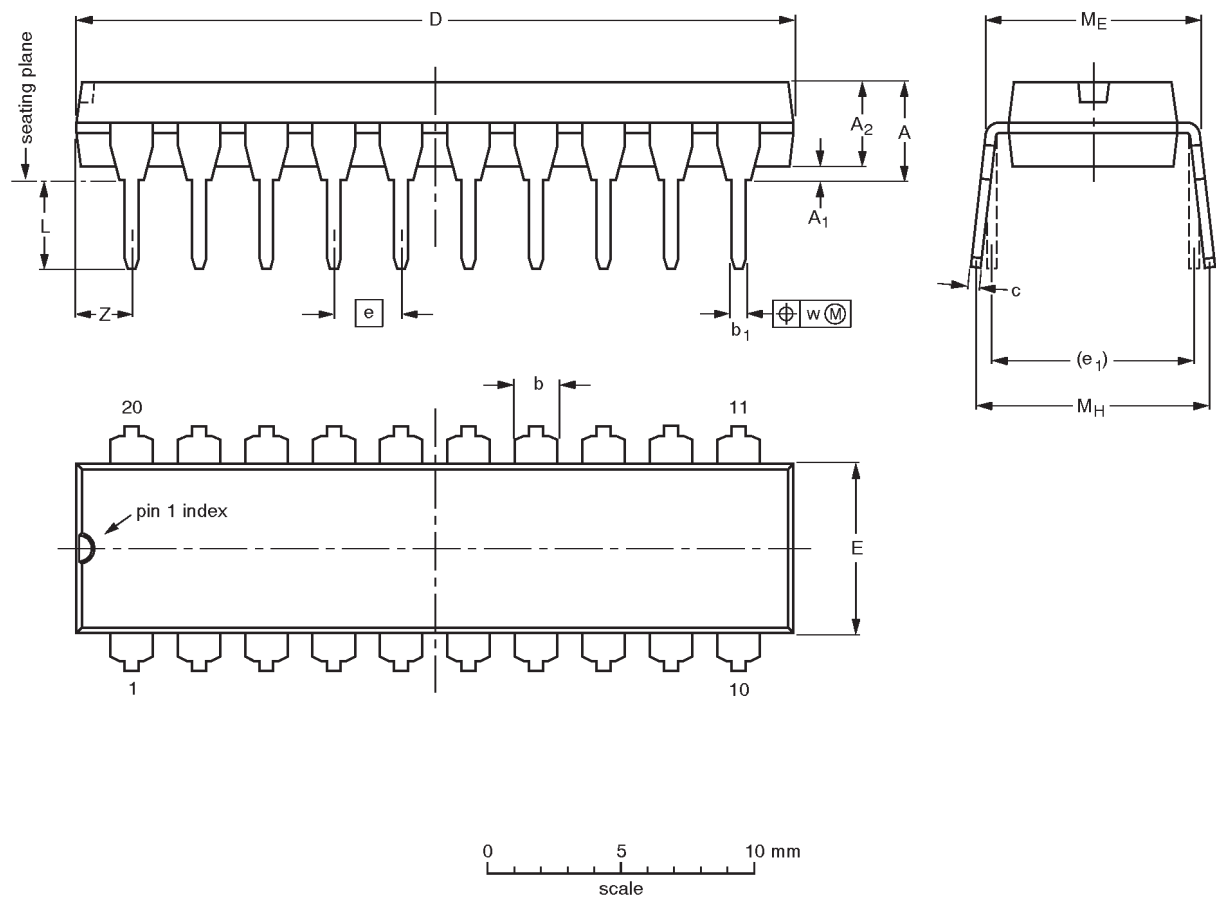
SF00006

Hex 2-input NAND drivers

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DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

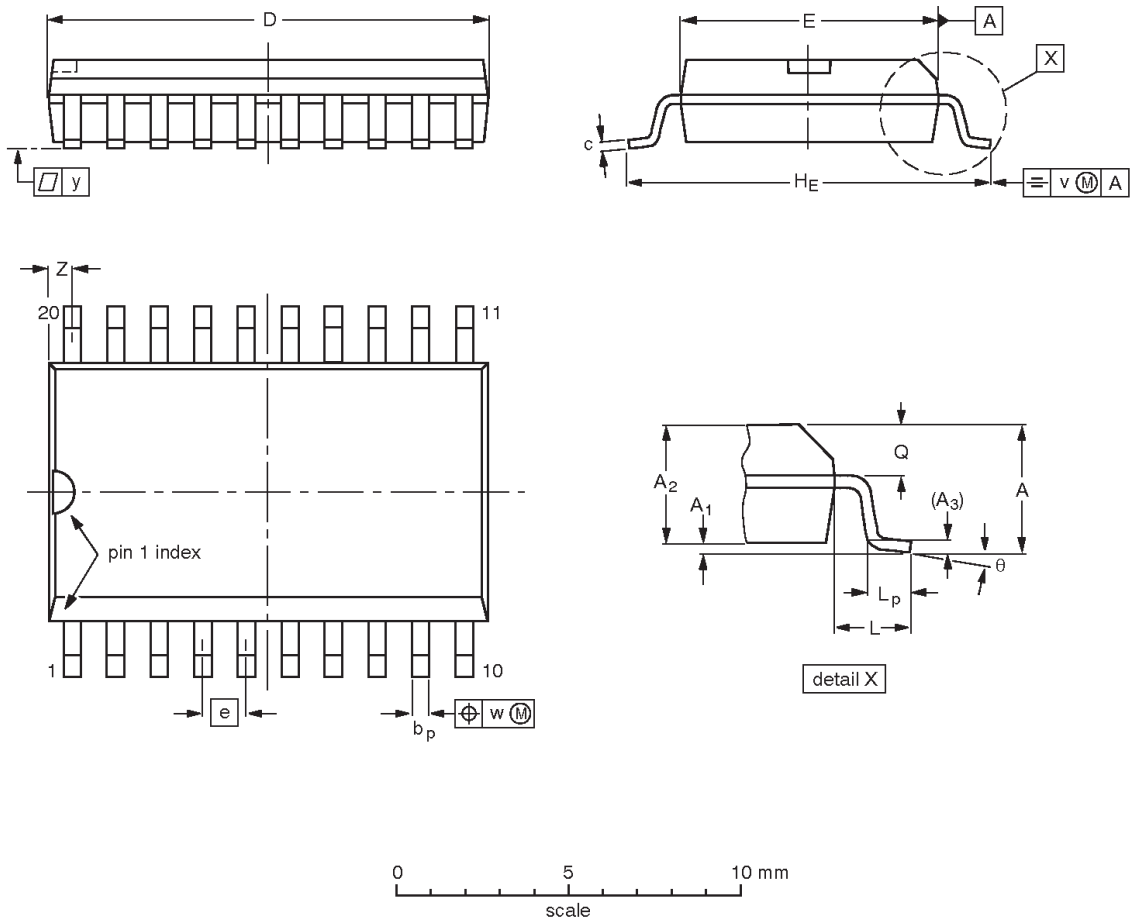
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT146-1			SC603			92-11-17 95-05-24

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SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				95-01-24 97-05-22

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Data sheet status

Data sheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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[1] Please consult the most recently issued datasheet before initiating or completing a design.

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